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128-27**THERMALLY CONDUCTIVE LOW STRESS EPOXY**

DESCRIPTION: 128-27 is a one component, thermally conductive, low stress, low shrink potting compound, glob top, and adhesive. 128-27 features *exceptional* resistance to thermal cycling. Recommended applications include potting, molding and encapsulation of electronics or stress sensitive components. 128-27 can also be used as an adhesive for bonding stress sensitive substrates.

PROPERTIES:

Color	Black
Viscosity (cps, 25°C)	300,000
Dielectric Strength (volts/mil)	490
Volume Resistivity (Ω -cm)	1×10^{14}
Dielectric Constant (1 kHz)	4.4
Dielectric Factor (60 Hz)	0.012
Thermal Conductivity (W/m-K)	1.55
Glass Transition Temp. (°C)	166
CTE α_1 (ppm/°C)	9
α_2 (ppm/°C)	45
Hardness (Shore D)	80 @ Room Temperature 70 @ 121°C
Useful Temperature Range (°C)	-55° to +280
Thermal Stability (°C)	Good to +330

HANDLING & CURING INSTRUCTIONS: Material is ready to use as received. Store at low temperature to maintain consistent flow properties. Allow material to warm up to room temperature before opening container.

SUGGESTED CURE SCHEDULES:

1 hour @ 121°C
30 minutes @ 150°C
5 minutes @ 180°C
2 minutes @ 200°C

*Snap cures require preheated substrates

End user is advised to experimentally determine the optimal time and temperature for cure for each individual application.

STORAGE: Shelf Life: up to 4 days at 25°C; or 6 months at 0°C; or 12 months at -10°C.

SAFETY & HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to results or possible infringements on patents.

REVISION DATE: 11/01/19 REVISION: A